

# Characterization of the thermal properties of OFHC copper at cryogenic temperature

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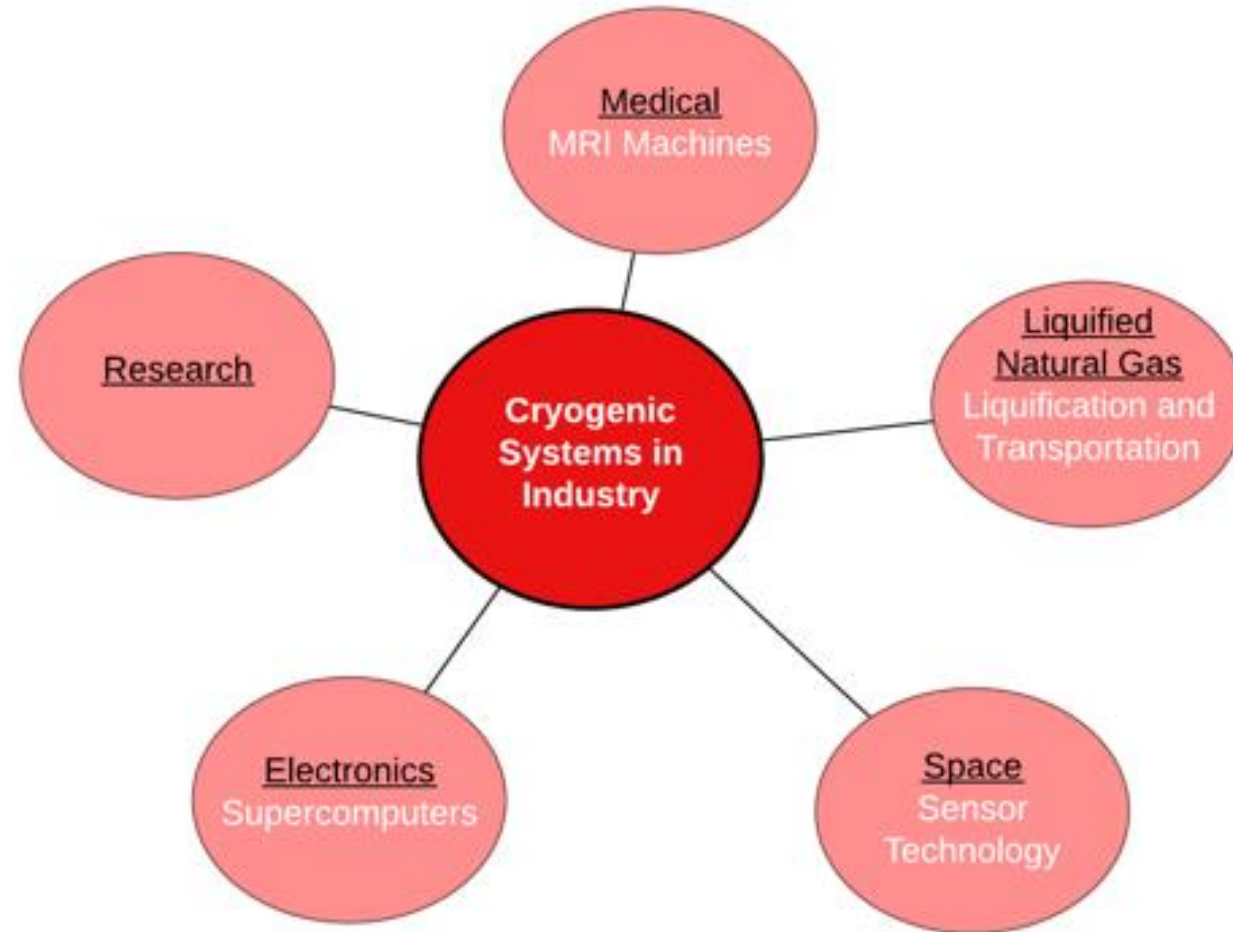
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and K McCusker

This work was made possible through a  
collaboration with Northrop Grumman



# Applications

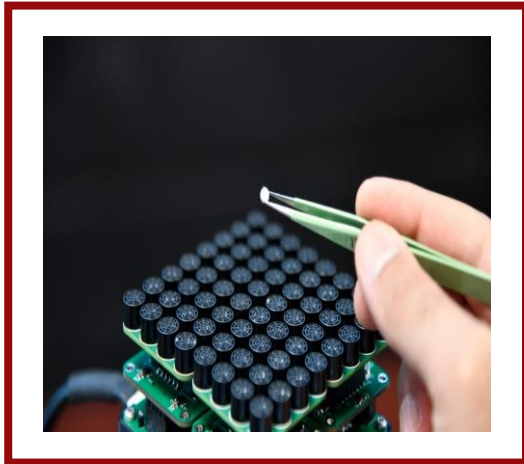
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# Cryogenic Cooling



Devices / Heat Sources

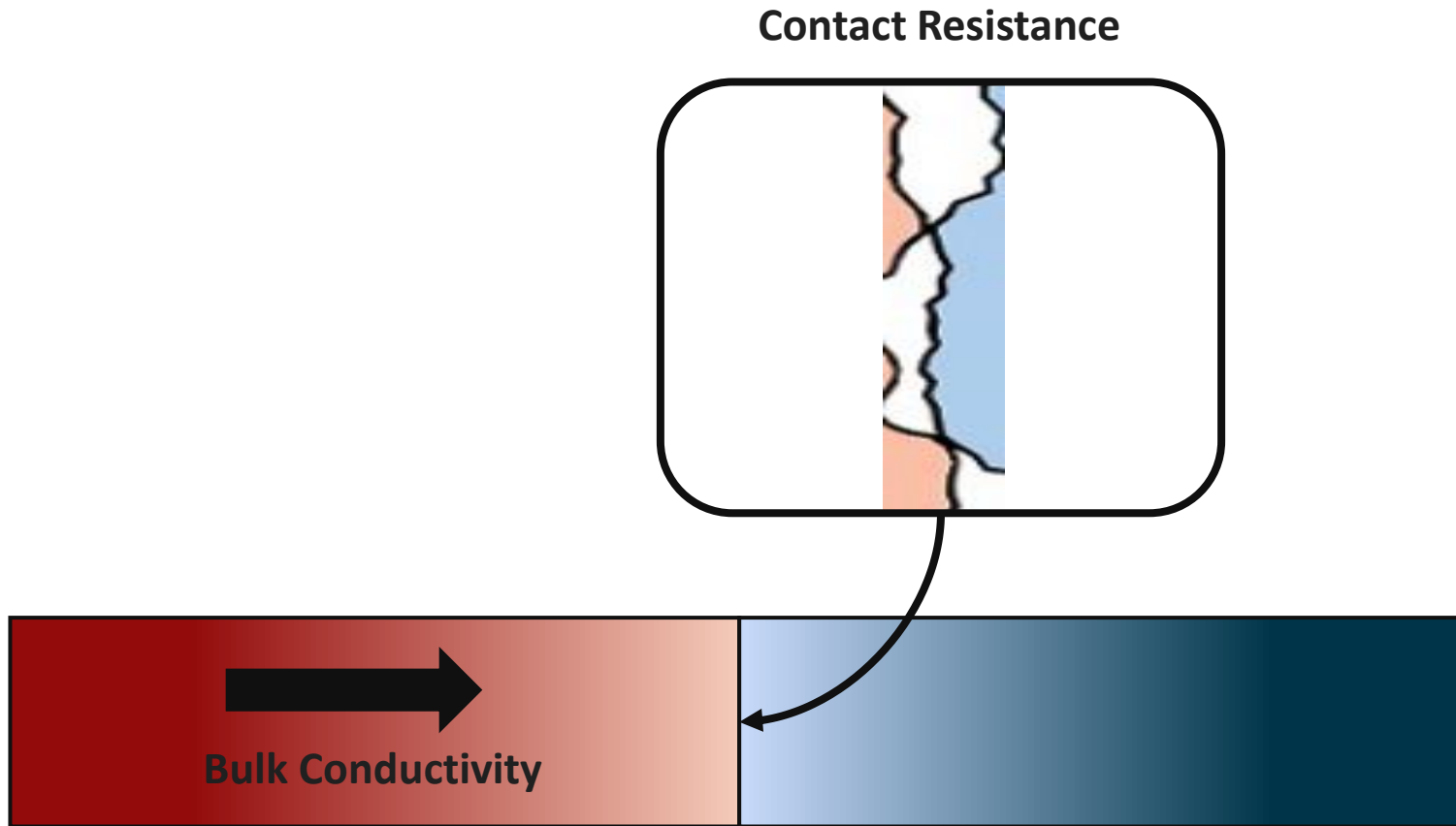


Heat Path

Cooling Device



# Heat Path





# Presentation Overview

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## 1. Bulk Thermal Conductivity

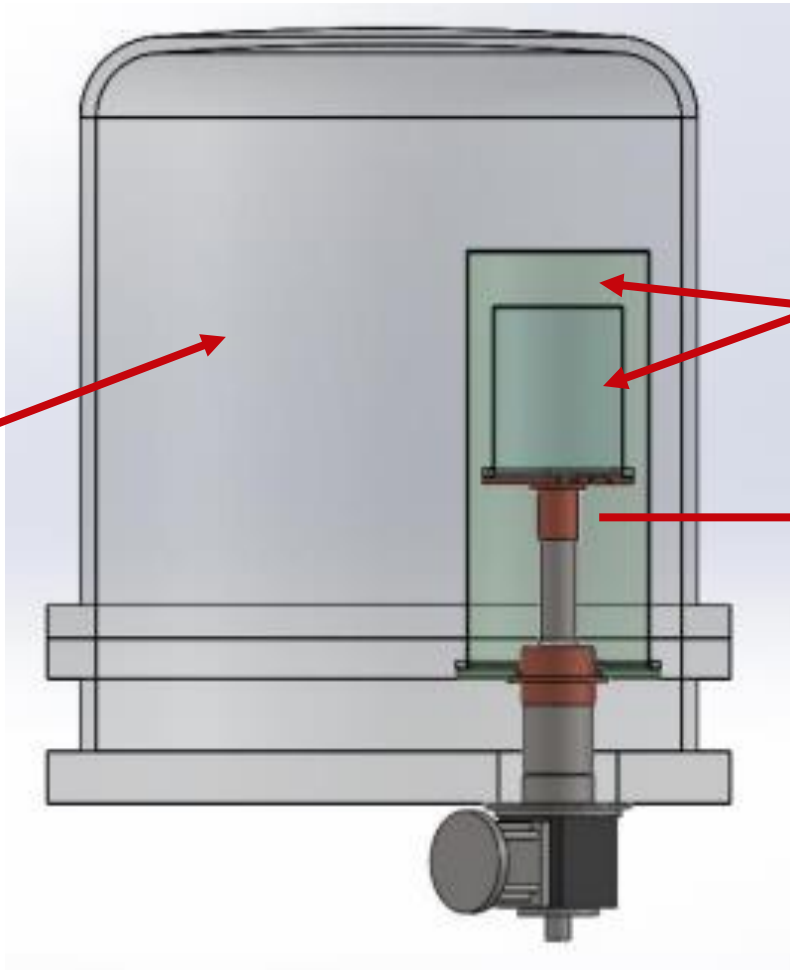
- Determine a range of thermal conductivity to expect from samples sourced from commercial vendors

## 2. Thermal Contact Resistance

- Determine the effect applied force has on thermal contact resistance

# System Overview

System held in a high vacuum



First and second stage thermal jackets covered with MLI



# Thermal Conductivity Experimental Setup

## Fourier's Law

$$Q = -kA \frac{\Delta T}{\Delta x}$$

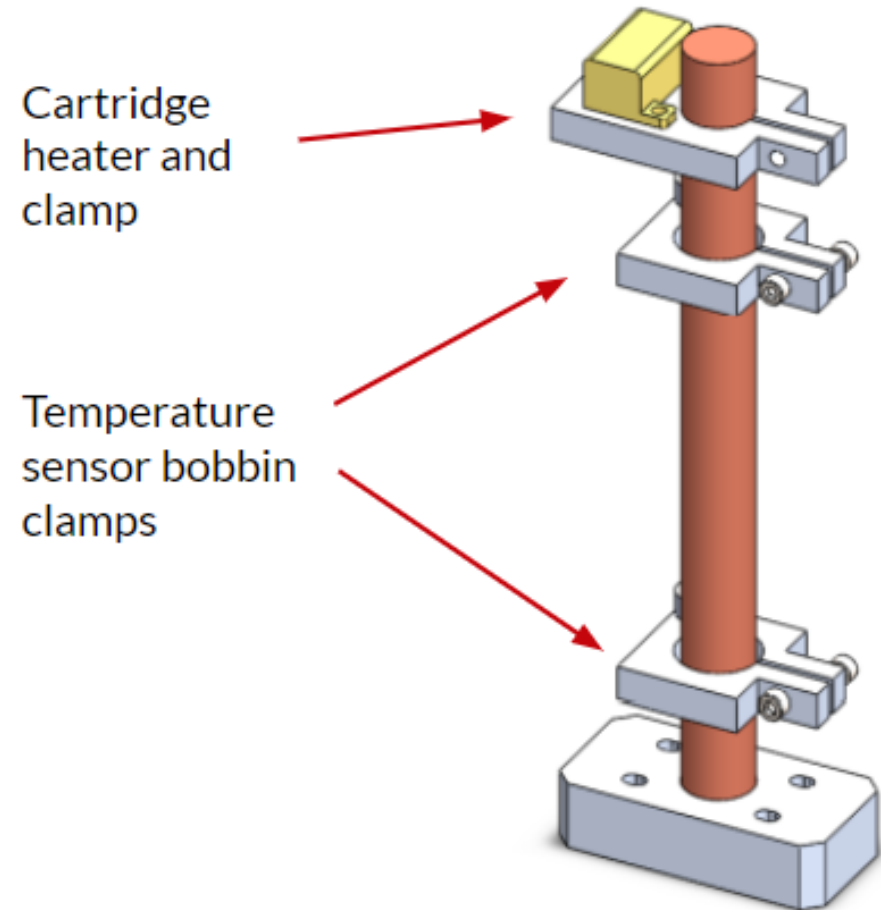
$Q$  is the heat input

$k$  is thermal conductivity

$A$  is cross sectional area

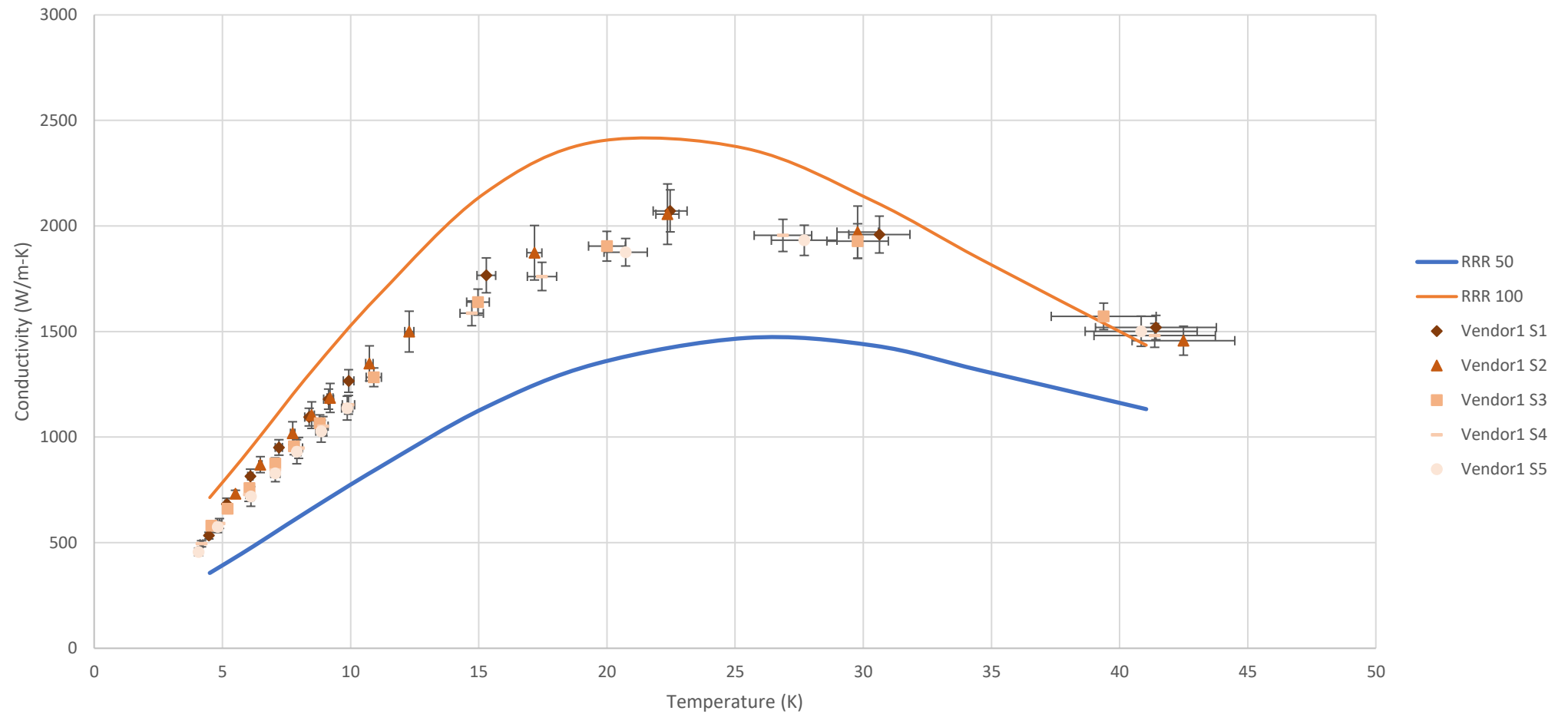
$\Delta T$  is the measured temperature difference

$\Delta x$  is the distance between temperature measurements





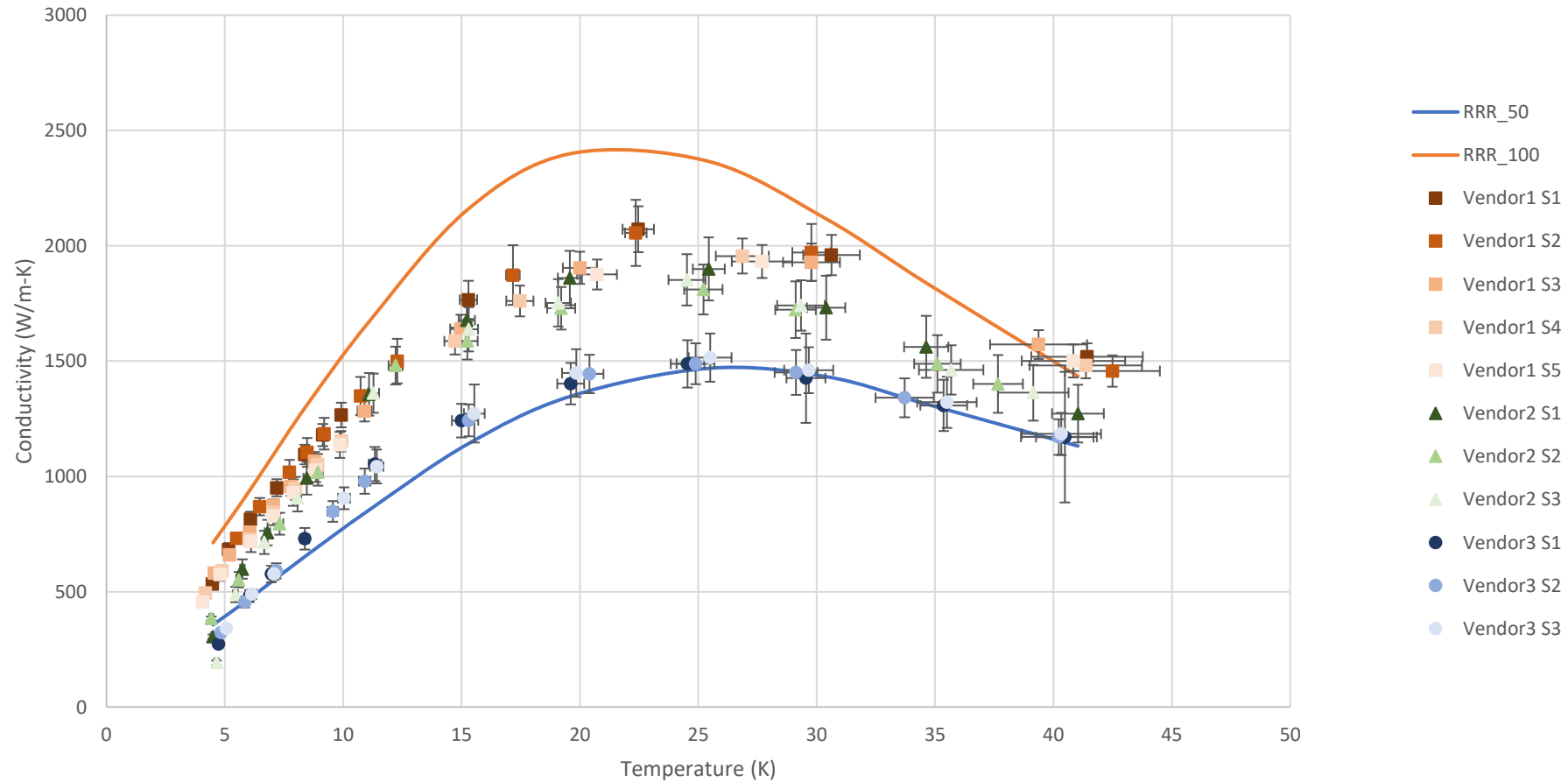
# Thermal Conductivity Results







# Thermal Conductivity Results



# Thermal Contact Resistance Experimental Setup

$$R = \frac{A(\Delta T - \Delta T_{bulk})}{Q - Q_{fixture}}$$

$R$  is contact resistance

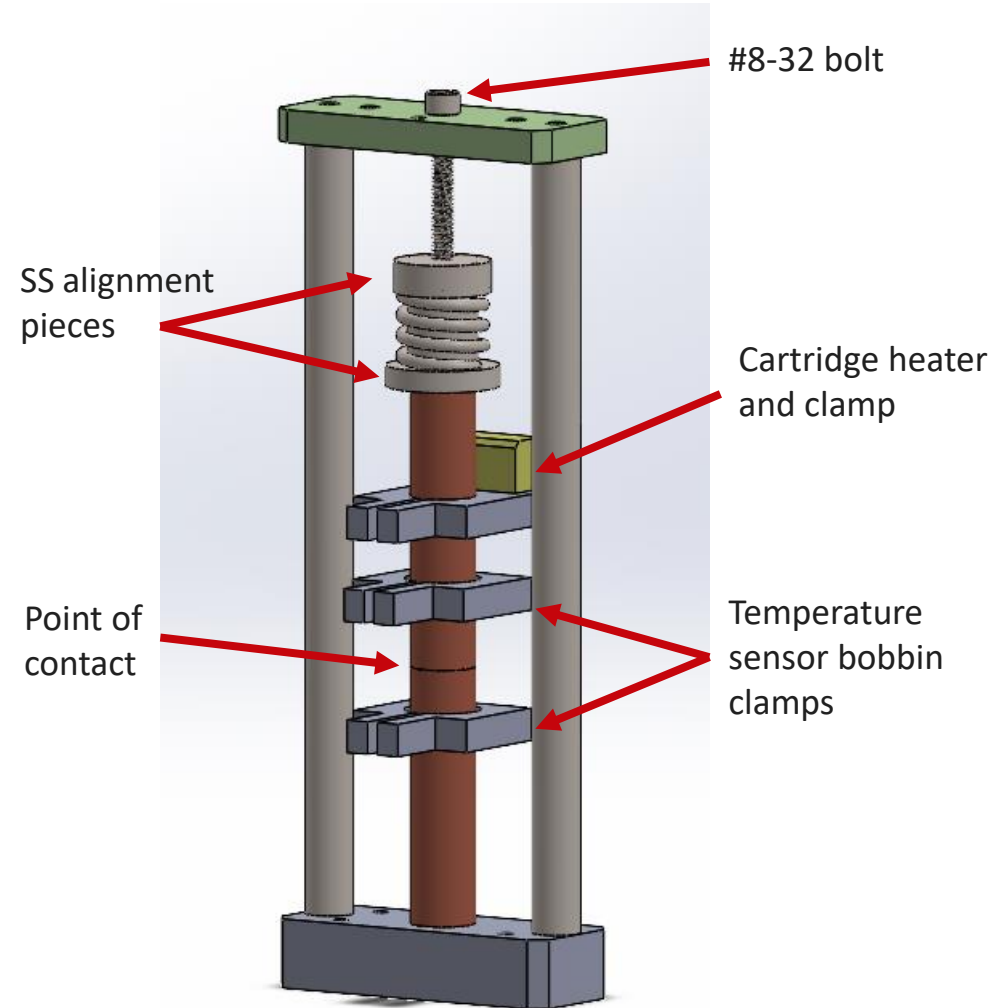
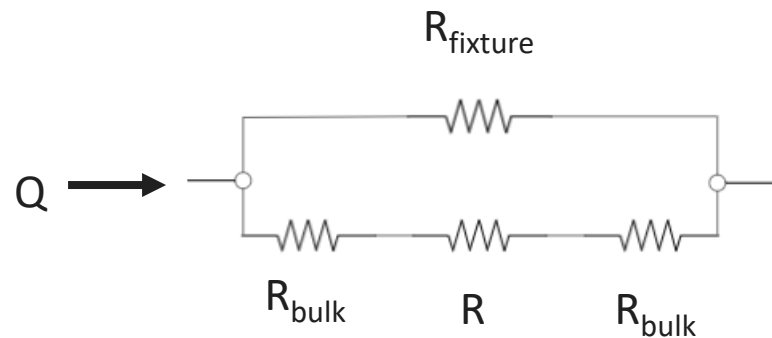
$\Delta T$  is measured temperature across point of contact

$\Delta T_{bulk}$  is the temperature drop in bulk material

$Q$  is the heat input

$Q_{fixture}$  is heat flow through fixture

$A$  is the sample cross sectional area

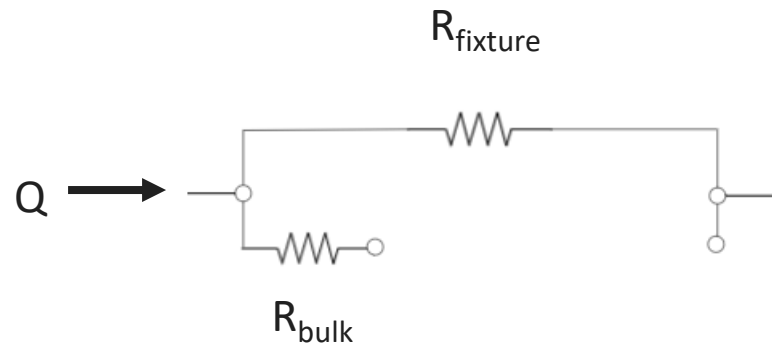


# Heat Flow Through Fixture

$$Q_{\text{fixture}} = \frac{\Delta T_{\text{fixture}}}{R_{\text{fixture}}}$$

$\Delta T_{\text{fixture}}$  is the temperature drop through the fixture

$R_{\text{fixture}}$  is the thermal resistance of the fixture



# Temperature Drop Through Bulk Material

$$\Delta T_{bulk} = \frac{(Q - Q_{fixture})L}{kA}$$

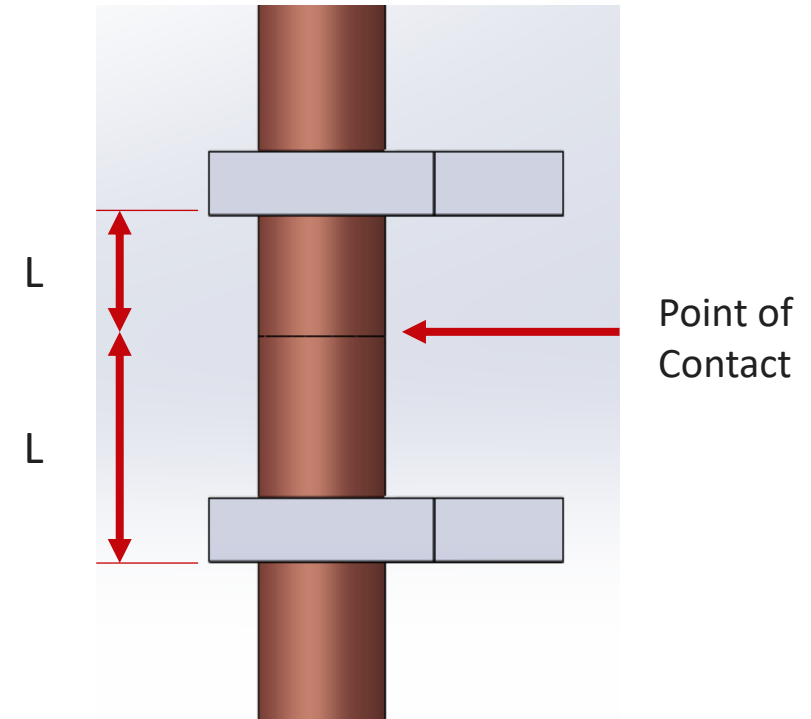
L is the distance between temperature sensor and point of contact

k is the conductivity of the sample

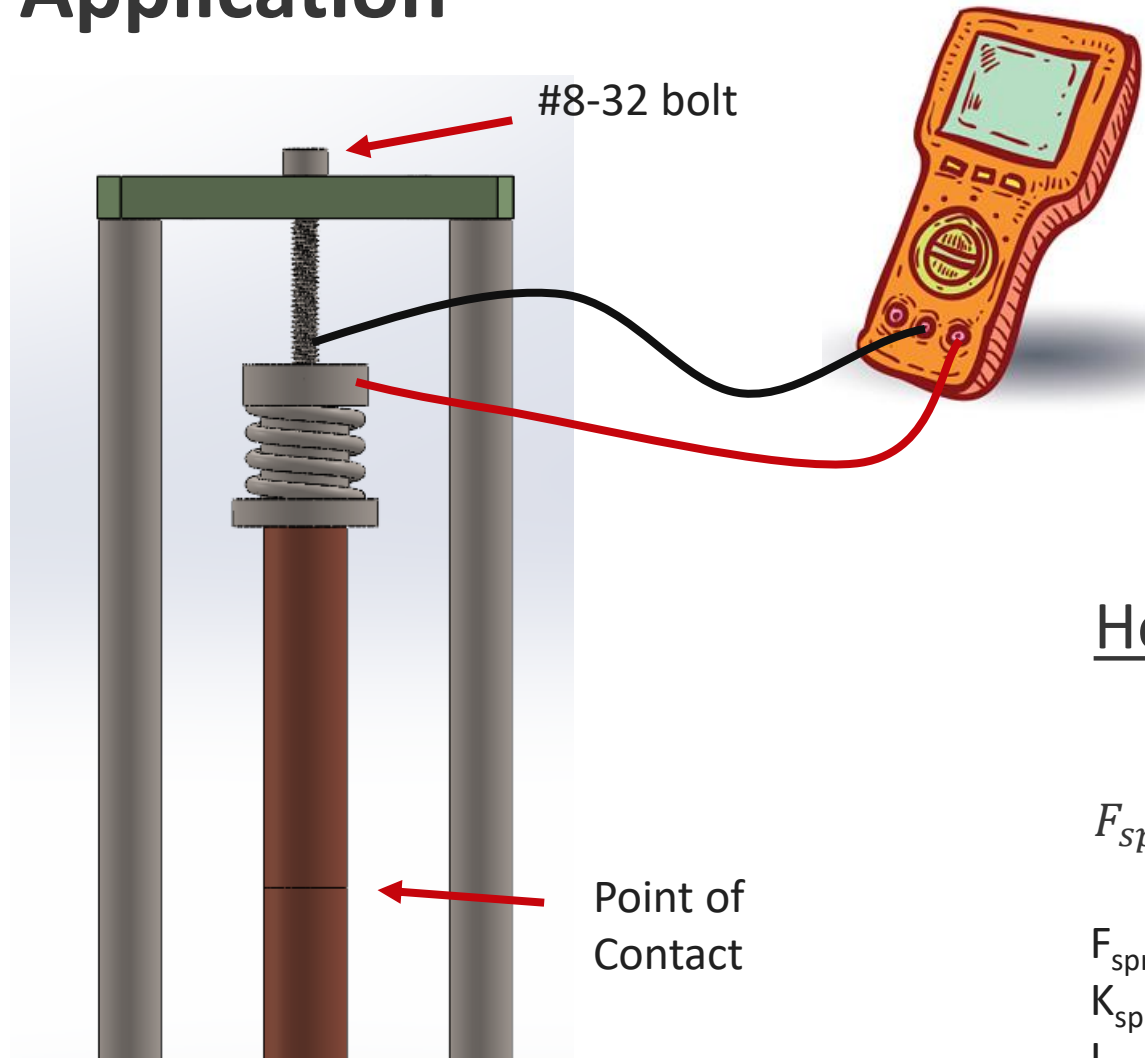
Q is the heat input

$Q_{fixture}$  is heat flow through fixture

A is cross sectional area



# Force Application



Hand-held multimeter used to detect continuity to determine contact

## Hooke's Law

$$F_{spring} = k_{spring}(L_{free} - L)$$

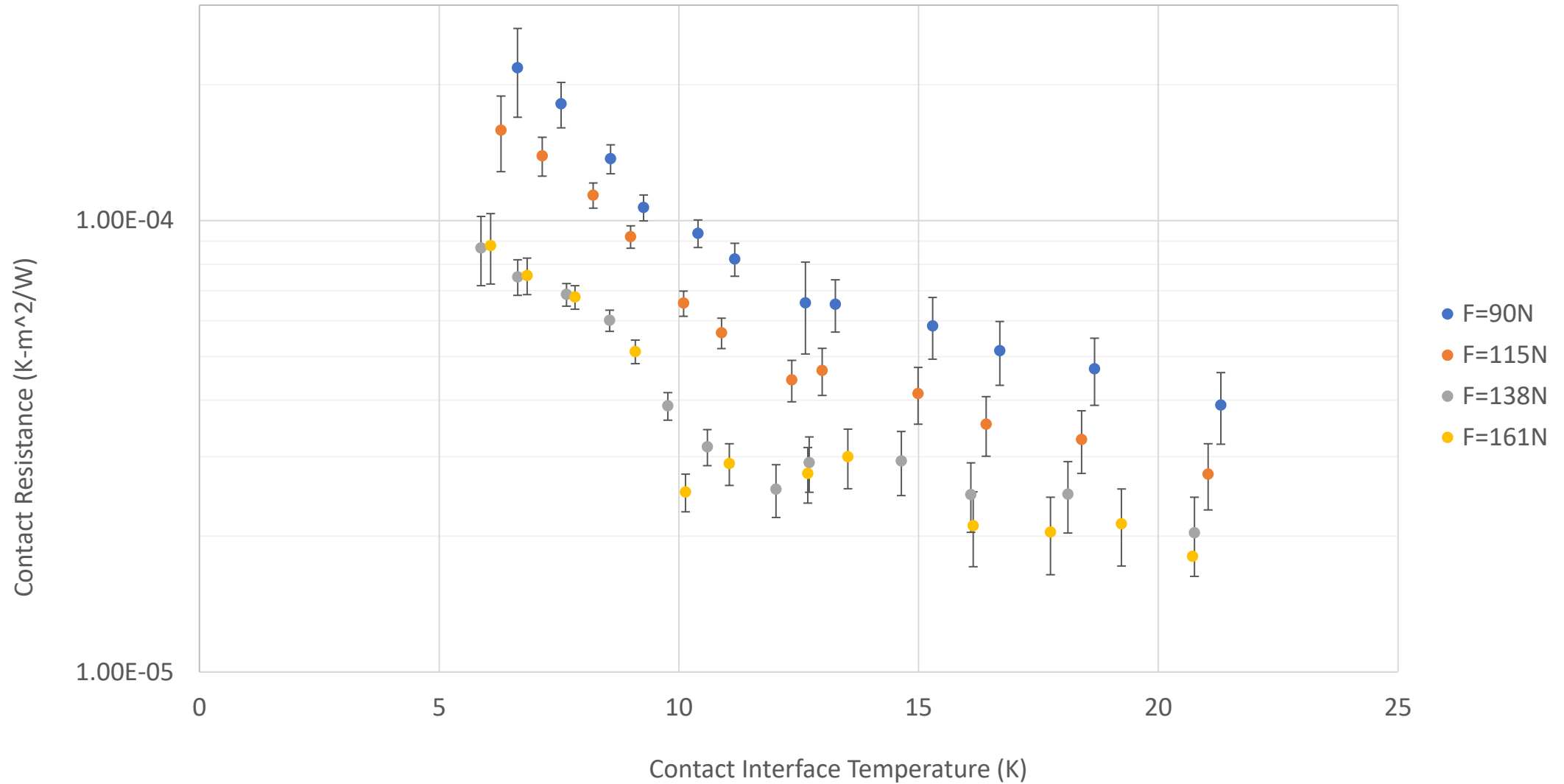
$F_{spring}$  is the spring force

$K_{spring}$  is the spring constant - 18.6 N/m

$L_{free}$  is the spring's free length - 2.54 cm

$L$  is the spring length

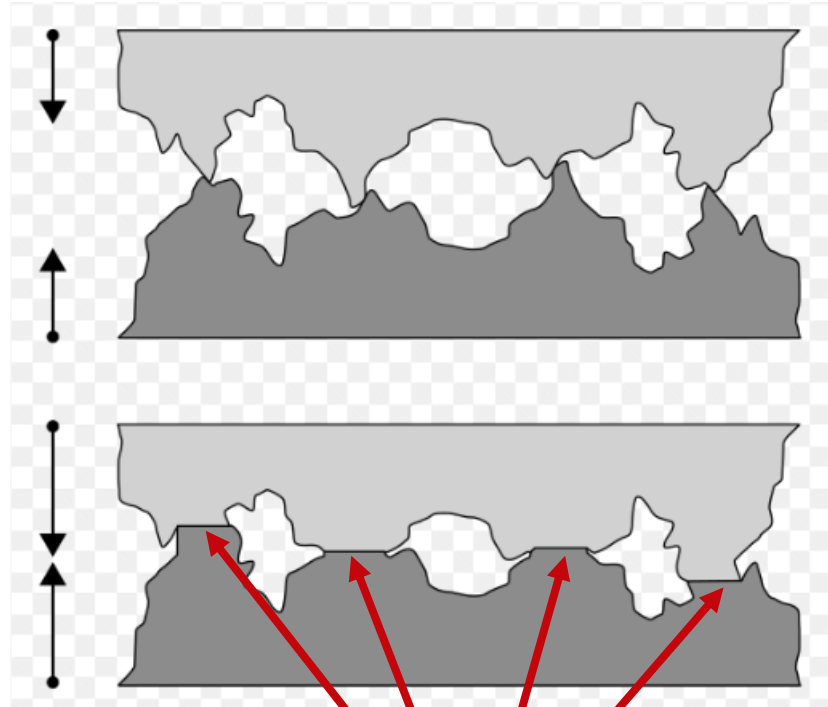
# Thermal Contact Resistance Results



# Asperity Deformation

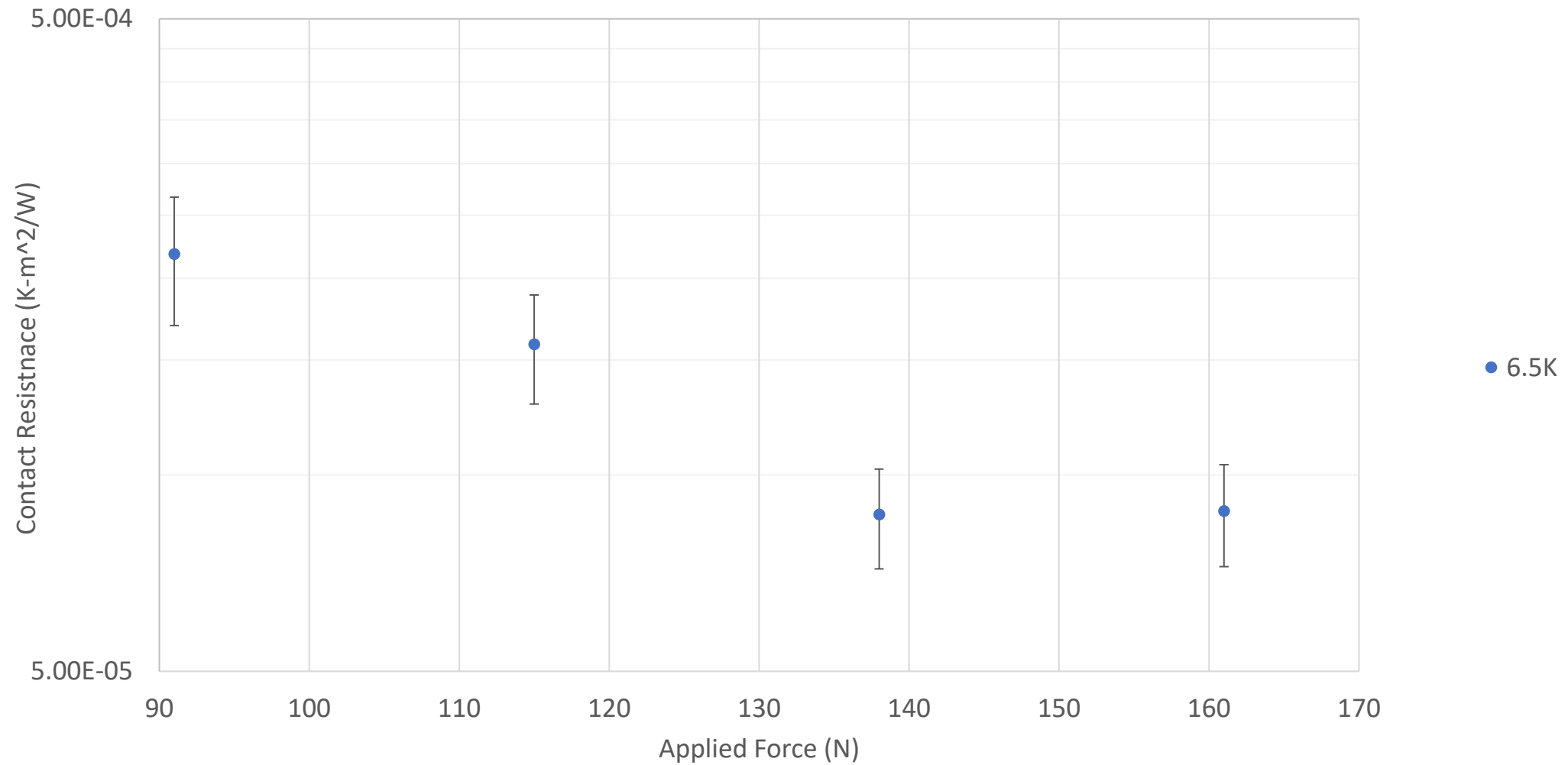


Applied Force  
Increases



Contact Area Increases

# Thermal Contact Resistance and Force Relation





# Conclusion

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## Bulk Conductivity:

- Samples from the same vendor have very similar values of conductivity
- The conductivity of OFHC copper sourced from commercial vendors is expected to be in the RRR range of 50 – 75

## Contact Resistance:

- Generally, as force at the contact surface increases, contact resistance decreases
- At higher forces, contact resistance begins to converge to a constant value